

# **Precision Adjustable Current-Limited Power-Distribution Switches**

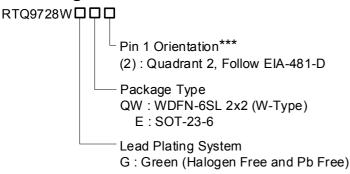
## **General Description**

The RTQ9728W is a cost effective, low voltage, P-MOSFET power switch IC with an adjustable current-limit feature. Low on-resistance ( $120m\Omega$  typ.) and low supply current ( $120\mu$ A typ.) are designed in this IC.

The RTQ9728W can offer an adjustable current-limit threshold between 0.1A and 2.5A (typ.) via an external resistor. The  $\pm 10\%$  current-limit accuracy can be realized for all current-limit settings.

The RTQ9728W is an ideal solution for power supply applications since it is functional for various current-limit requirements. It is available in WDFN-6SL 2x2 and SOT-23-6 packages.

## **Ordering Information**



#### Note:

\*\*\*Empty means Pin1 orientation is Quadrant 1

Richtek products are:

- RoHS compliant and compatible with the current requirements of IPC/JEDEC J-STD-020.
- ▶ Suitable for use in SnPb or Pb-free soldering processes.

## **Features**

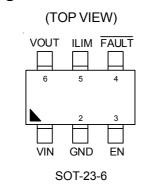
- Adjustable Current Limit: 0.1A to 2.5A (typ.)
- ±10% Current-Limit Accuracy @2A Over Temperature
- 150mΩ (max) P-MOSFET
- Low Supply Current: 120μA
- Input Operating Voltage Range: 2.5V to 6V
- Reverse Input-Output Voltage Protection
- Built-in Soft-Start
- 15-kV ESD Protection per IEC 61000-4-2 (With External Capacitance)
- Nemko Approved IEC62368-1
- RoHS Compliant and Halogen Free

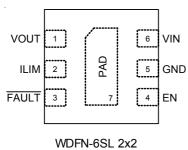
## **Applications**

- Digital TVs
- Set Top Boxes
- VOIP Phones



# Pin Configuration





# **Marking Information**

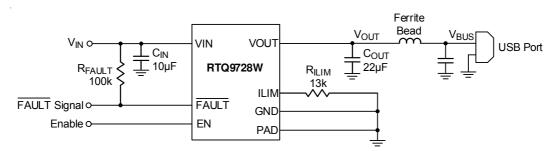
RTQ9728WGQW 4WW

4W : Product Code W : Date Code



7K= : Product Code DNN : Date Code

# **Typical Application Circuit**



Note :  $R_{ILIM}$  = 13k $\Omega$  for 2A Power Switch Operation

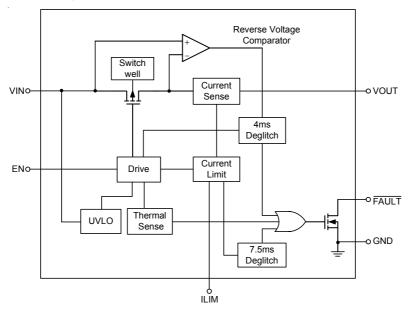


# **Functional Pin Description**

F	Pin No.		Pin No. Pin		Din Franchism			
SOT-23-6	WDFN-6SL 2x2	Name	Pin Function					
1	6	VIN	Power input. Connect a $10\mu F$ or greater ceramic capacitor from the VIN to GND as close to the IC as possible.					
2	5	GND	GND Ground.					
3	4	EN	Enable control input. Logic high turns on the power switch.					
4	3	FAULT	Active-low open-drain output. Asserted during over-current, over-temperature, or reverse-voltage conditions.					
5	2	ILIM	Current limit setting. Connect an external resistor to set current-limit threshold. The recommended resistance range is $10k\Omega \le R_{ILIM} \le 226k\Omega$ .					
6	1	VOUT	Output.					
	7 (Exposed Pad)	PAD	Exposed pad. The exposed pad is internally unconnected and must be soldered to a large GND plane. Connect this GND plane to other layers with thermal vias to help dissipate heat from the device.					



# **Functional Block Diagram**



## **Operation**

The RTQ9728W is a current-limited power switch using P-MOSFETs for applications where short-circuit or heavy capacitive loads will be encountered. These devices allow users to adjust the current-limit threshold between 100mA and 2.5A (typ.) via an external resistor. Additional device shutdown features include over-temperature protection and reverse-voltage protection.

The RTQ9728W provides built-in soft-start function. The driver controls the gate voltage of the power switch. The driver incorporates circuitry that controls the rising time and falling time of the output voltage to limit large inrush current and voltage surges. The RTQ9728W enters constant-current mode when the load exceeds the current-limit threshold.



# Absolute Maximum Ratings (Note 1)

• Voltage Range On VIN, VOUT, EN, FAULT, ILIM	-0.3V to $6.5V$
<10ms	-0.3V to 7V
<ul> <li>Power Dissipation, P<sub>D</sub> @ T<sub>A</sub> = 25°C</li> </ul>	
SOT-23-6	0.48W
WDFN-6SL 2x2	2.98W
Package Thermal Resistance (Note 2)	
SOT-23-6, $\theta_{JA}$	208.2°C/W
WDFN-6SL 2x2, $\theta_{JA}$	
WDFN-6SL 2x2, $\theta_{\text{JC}}$	
• Lead Temperature (Soldering, 10 sec.)	
• Junction Temperature	
Storage Temperature Range	$-65^{\circ}\text{C}$ to $150^{\circ}\text{C}$
ESD Susceptibility (Note 3)	
HBM (Human Body Model)	2kV
CDM (Charged Device Model)	500V
IEC 61000-4-2 Contact Discharge (Note 7)	8kV
IEC 61000-4-2 Air-Gap Discharge (Note 7)	15kV

# **Recommended Operating Conditions** (Note 4)

- Supply Input Voltage, VIN ----- 2.5V to 6V
- Temperature Range Junction ----- -40°C to 125°C

## **Electrical Characteristics**

 $(V_{IN} = 5V, T_A = T_J = -40^{\circ}C$  to 125°C, unless otherwise specified)

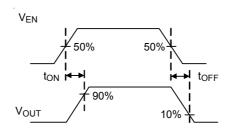
Parameter		Symbol	Test Conditions	Min	Тур	Max	Unit	
Shutdown Current		Ishdn	V <sub>EN</sub> = 0V, I <sub>OUT</sub> = 0A		1	10	μΑ	
Quiescent Cu	rrent	IQ	I <sub>OUT</sub> = 0A		120	300	μΑ	
EN Input	Logic-High	VIH		1.2		-	V	
Voltage	Logic-Low	VIL				0.4	V	
EN Input Curr	ent	I <sub>EN</sub>	V <sub>IN</sub> = 5.5V V <sub>EN</sub> = 0V or 5.5V		0.02	0.5	μΑ	
Reverse Leak	Reverse Leakage Current		V <sub>OUT</sub> = 5V, V <sub>IN</sub> = 0V		1	10	μΑ	
	Under-Voltage Lockout Threshold		VIN rising, $0^{\circ}C \le T_{J} \le 125^{\circ}C$		2.3	2.5		
_			VIN rising, –40°C ≤ T <sub>J</sub> ≤ 125°C		2.3	2.6	V	
Trireditora			VIN falling		2.1			
FAULT Output Low Voltage		V <sub>OL</sub>	I <sub>FAULT</sub> = 1mA			180	mV	
FAULT Off State Leakage			V <sub>FAULT</sub> = 5.5V			1	μА	
FAULT Deglitch			FAULT assertion or de-assertion due to reverse voltage condition	2	4	6	me	
FAULT Degili	CII		FAULT assertion or de-assertion due to over-current condition	2	7.5	20	ms	

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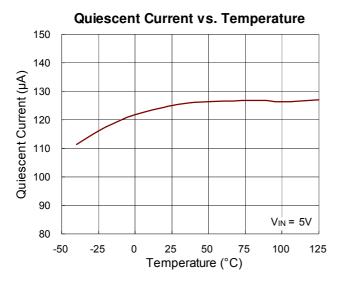
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
FAULT Flag Assertion Offset	V <sub>FAULT_OFS</sub>	Offset between fault flag assertion level versus ILIM trigger level (Note 5)	-100	1	0	mA
Turn On Time	Ton	Co = 1E. Dr. = 1000 (Note 6)	-	-	0.3	mo
Turn Off Time	T <sub>OFF</sub>	$C_0 = 1\mu F, R_L = 100\Omega$ (Note 6)		-	0.45	ms
Static Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	I <sub>OUT</sub> = 0.2A		120	150	mΩ
Reverse Voltage Comparator Trip Point	IREV_HYS	Vout – Vin	100	135	300	mV
		R <sub>ILIM</sub> = 13kΩ	1800	2000	2200	
Current Limit	ILIM	$R_{ILIM}$ = 13k $\Omega$ , $T_A$ = 25°C	1840	2000	2160	mA
		$R_{\text{ILIM}} = 49.9 \text{k}\Omega$	460	520	572	
Response Time to Short Circuit	tios	V <sub>IN</sub> = 5V (Note 5)	-	2	-	μS
Thermal Shutdown Temperature	T <sub>SD</sub>	(Note 5)	-	160		°C
Thermal Shutdown Hysteresis	$\Delta T_{SD}$	(Note 5)		20		°C

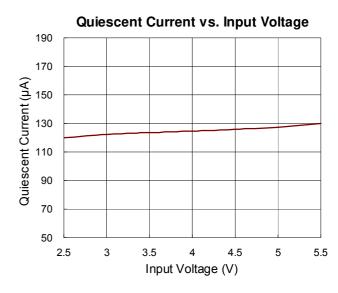
- **Note 1.** Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
- Note 2.  $\theta_{JA}$  is measured under natural convection (still air) at  $T_A$  = 25°C with the component mounted on a high effective-thermal-conductivity four-layer test board on a JEDEC 51-7 thermal measurement standard.  $\theta_{JC}$  is measured at the exposed pad of the package. The PCB copper area with exposed pad is 70mm<sup>2</sup>.
- Note 3. Devices are ESD sensitive. Handling precautions are recommended.
- Note 4. The device is not guaranteed to function outside its operating conditions.
- Note 5. Guarantee by design.
- Note 6. Test Circuit and Voltage Waveforms
- Note 7. Surges per EN61000-4-2. 1999 applied to output terminals of EVM. These are passing test levels, not failure threshold.

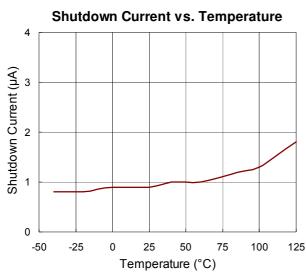


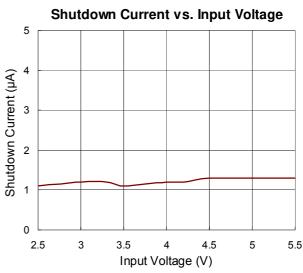


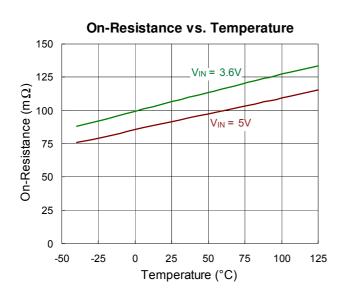
# **Typical Operating Characteristics**

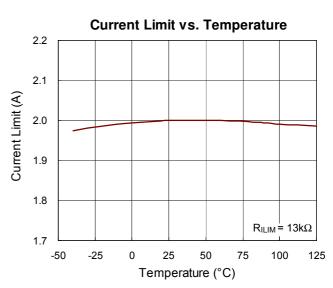






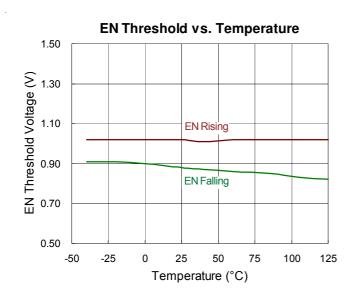


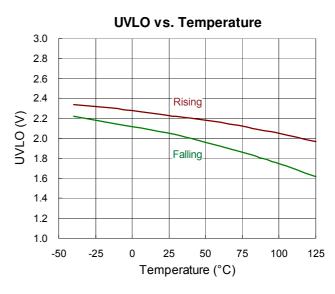


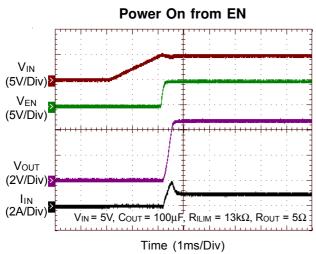


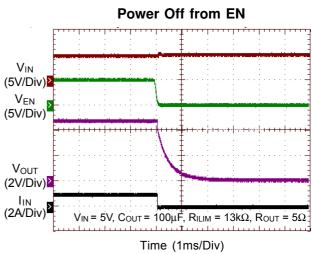
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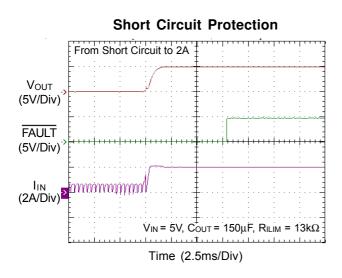


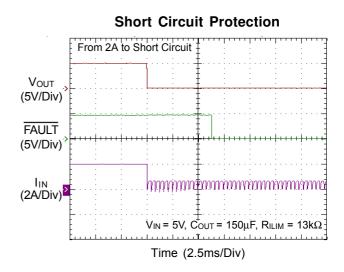




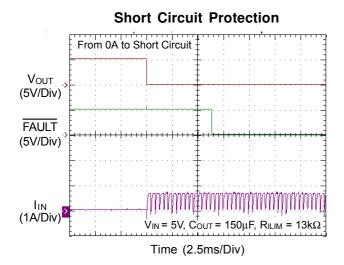


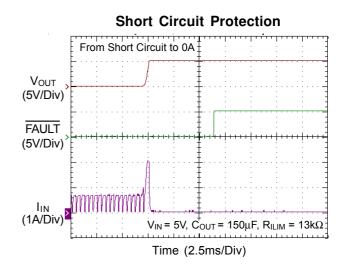


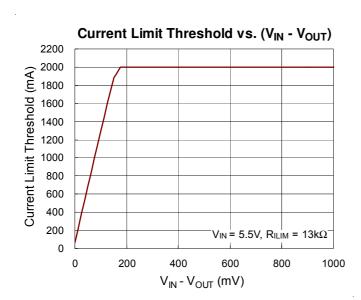


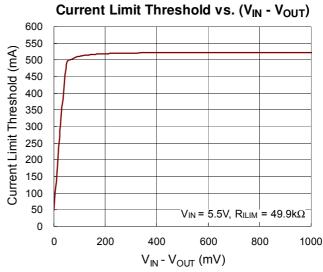


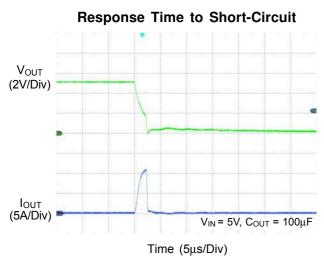


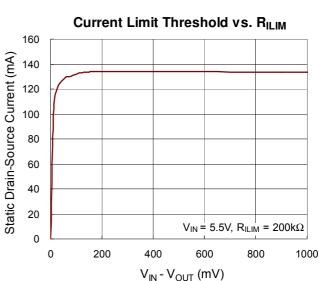












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## **Application Information**

Richtek's component specification does not include the following information in the Application Information section. Thereby no warranty is given regarding its validity and accuracy. Customers should take responsibility to verify their own designs and to ensure the functional suitability of their components and systems.

The RTQ9728W is a single P-MOSFET high side power switch with active high enable input, optimized for self-powered and bus-powered Universal Serial Bus (USB) applications. The switch's low R<sub>DS(ON)</sub> meets USB voltage drop requirements and a flag output is available to indicate fault conditions to the local USB controller.

## **Current Limiting and Short Circuit Protection**

When a heavy load or short circuit situation occurs while the switch is enabled, large transient current may flow through the device. The RTQ9728W includes a current-limit circuitry to prevent these large currents from damaging the MOSFET switch and the hub downstream ports. The RTQ9728W provides an adjustable current-limit threshold between 0.1A and 2.5A (typ.) via an external resistor,  $R_{\rm ILIM}$ , between  $10 k\Omega$  and  $226 k\Omega$ . The maximum -100 mA fault flag assertion offset needs cautions, especially for very low ILIM applications. Taking the application of ILIM = 250 mA as an example, the minimum fault flag assertion level might be 150 mA (40% error versus its target).Once the current-limit threshold is exceeded, and output voltage does not drop over 1/2 input voltage, the device enters constant current mode.

If output voltage drops under around 1/2 input voltage, the device enters re-soft start current fold-back mode until either thermal shutdown occurs or the fault is removed. Table1 shows a recommended current-limit value vs.  $R_{\rm ILIM}$  resistor.

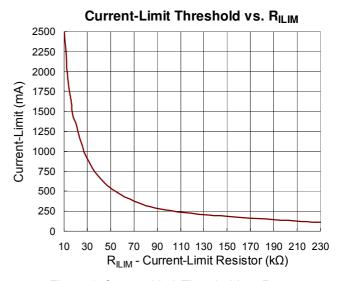


Figure 1. Current-Limit Threshold vs. R<sub>ILIM</sub>



Table 1. Recommended R<sub>ILIM</sub> Resistor Selections

Desired Nominal	Ideal Resistor	Closet 1% Resistor	Actual Limits (Include R Tolerance)					
Current Limit (mA)	$(k\Omega)$	(kΩ)	IOS min (mA)	IOS nom (mA)	IOS max (mA)			
120	226.1	226.0	101.3	120.0	142.1			
200	134.0	133.0	173.7	201.5	233.9			
300	88.5	88.7	262.1	299.4	342.3			
400	65.9	66.5	351.1	396.7	448.7			
500	52.5	52.3	443.9	501.6	562.4			
600	43.5	43.2	535.1	604.6	674.1			
700	37.2	37.4	616.0	696.0	776.0			
800	32.4	32.4	708.7	800.8	892.9			
900	28.7	28.7	797.8	901.5	1005.2			
1000	25.8	26.1	875.4	989.1	1102.8			
1100	23.4	23.2	982.1	1109.7	1237.3			
1200	21.4	21.5	1057.9	1195.4	1332.9			
1300	19.7	19.6	1158.0	1308.5	1459.0			
1400	18.5	18.7	1225.7	1385.0	1544.3			
1500	17.3	17.4	1317.3	1488.5	1659.7			
1600	16.2	16.2	1414.8	1598.7	1782.6			
1700	15.2	15.0	1528.1	1726.7	1925.3			
1800	14.4	14.3	1602.9	1811.2	2019.5			
1900	13.6	13.7	1673.1	1890.5	2107.9			
2000	12.9	13.0	1763.2	1992.3	2221.4			
2100	12.3	12.4	1848.5	2088.7	2328.9			
2200	11.8	11.8	1942.6	2195.0	2447.4			
2300	11.3	11.3	2028.4	2292.0	2555.6			
2400	10.8	10.7	2141.7	2420.0	2698.3			
2500	10.3	10.0	2292.2	2590.0	2887.9			



#### Fault Flag

The RTQ9728W provides a FAULT signal pin which is an N-Channel open-drain MOSFET output. This open-drain output goes low when current exceeds current-limit threshold. The FAULT output is capable of sinking a 1mA load to typically 180mV above ground. The FAULT pin requires a pull-up resistor; this resistor should be large in value to reduce energy drain. A 100k $\Omega$  pull-up resistor works well for most applications. In case of an over-current condition, FAULT will be asserted only after the flag response delay time, t<sub>D</sub>, has elapsed. This ensures that FAULT is asserted upon valid over-current conditions and that erroneous error reporting is eliminated. For example, false over-current conditions may occur during hot-plug events when extremely large capacitive loads are connected, which induces a high transient inrush current that exceeds the current limit threshold. The FAULT response delay time, t<sub>D</sub>, is typically 7.5ms.

#### Supply Filter/Bypass Capacitor

A  $10\mu F$  low-ESR ceramic capacitor connected from VIN to GND and located close to the device is strongly recommended to prevent input voltage drooping during hot plug events. However, higher capacitor values may be used to further reduce the voltage droop on the input. Without this bypass capacitor, an output short may cause sufficient ringing on the input (from source lead inductance) to destroy the internal control circuitry. Note that the input transient voltage must never exceed 6V as stated in the Absolute Maximum Ratings.

### **Output Filter Capacitor**

Standard bypass methods should be used to minimize inductance and resistance between the bypass capacitor and the downstream connector to reduce EMI and decouple voltage droop caused by hot-insertion transients in downstream cables. Ferrite beads in series with VBUS, the ground line and the bypass capacitors at the power connector pins are recommended for EMI and ESD protection. The bypass capacitor itself should have a low dissipation factor to allow decoupling at higher frequencies.

For commercial applications where the ambient temperature is 0°C to 70°C (such as a PC or USB hub), RTQ9728W supports an output capacitor range of up to

 $120\mu F$ . For industrial applications with an ambient temperature of  $-40^{\circ}C\sim125^{\circ}C$ , please limit the output capacitance to less than 50uF to ensure normal startup.

#### **Chip Enable Input**

The RTQ9728W do not have auto discharge function. During shutdown condition, the supply current is  $1\mu A$ , typically. The maximum guaranteed voltage for a logic-low at the EN pin is 0.4V. A minimum guaranteed voltage of 1.2V at the EN pin will turn on the RTQ9728W. Floating the input may cause unpredictable operation.

#### **Under-Voltage Lockout**

Under-Voltage Lockout (UVLO) prevents the MOSFET switch from turning on until input voltage exceeds approximately 2.3V (typ.). If input voltage drops below approximately 2.1V (typ.), UVLO turns off the MOSFET switch.

#### **Thermal Considerations**

The junction temperature should never exceed the absolute maximum junction temperature  $T_{J(MAX)}$ , listed under Absolute Maximum Ratings, to avoid permanent damage to the device. The maximum allowable power dissipation depends on the thermal resistance of the IC package, the PCB layout, the rate of surrounding airflow, and the difference between the junction and ambient temperatures. The maximum power dissipation can be calculated using the following formula :

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$$

where  $T_{J(MAX)}$  is the maximum junction temperature,  $T_A$  is the ambient temperature, and  $\theta_{JA}$  is the junction-to-ambient thermal resistance.

For continuous operation, the maximum operating junction temperature indicated under Recommended Operating Conditions is 125°C. The junction-to-ambient thermal resistance,  $\theta_{JA}$ , is highly package dependent. For a SOT-23-6 package, the thermal resistance,  $\theta_{JA}$ , is 208.2°C/W on a standard JEDEC 51-7 high effective-thermal-conductivity four-layer test board. For a WDFN-6SL 2x2 package, the thermal resistance,  $\theta_{JA}$ , is 33.5°C/W on a standard JEDEC 51-7 high effective-thermal-conductivity four-layer test board. The maximum power dissipation at

DSQ9728W-07 February 2023

T<sub>A</sub> = 25°C can be calculated as below:

 $P_{D(MAX)}$  = (125°C - 25°C) / (208.2°C/W) = 0.48W for a SOT-23-6 package.

 $P_{D(MAX)}$  = (125°C - 25°C) / (33.5°C/W) = 2.98W for a WDFN-6SL 2x2 package.

The maximum power dissipation depends on the operating ambient temperature for the fixed  $T_{J(MAX)}$  and the thermal resistance,  $\theta_{JA}$ . The derating curves in Figure 2 allows the designer to see the effect of rising ambient temperature on the maximum power dissipation.

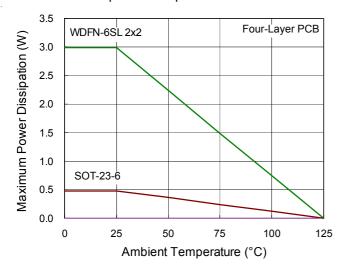


Figure 2. Derating Curve of Maximum Power Dissipation



#### **Layout Consideration**

Follow the PCB layout guidelines for optimal performance of the device.

- ▶ Place the R<sub>ILIM</sub> resistor as close to the device as possible to reduce parasitic effects on the current limit accuracy.
- For better thermal performance, design a wide and thick plane for PCB ground or add sufficient vias to GND plane.

An example of PCB layout guide is shown in Figure 3 and Figure 4.

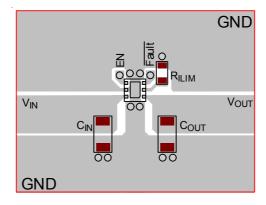


Figure 3. PCB Layout Guide for WDFN-6SL 2x2

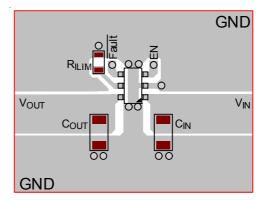
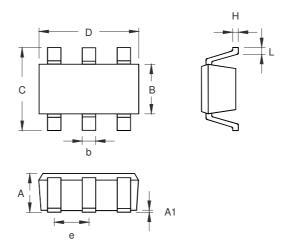


Figure 4. PCB Layout Guide for SOT-23-6

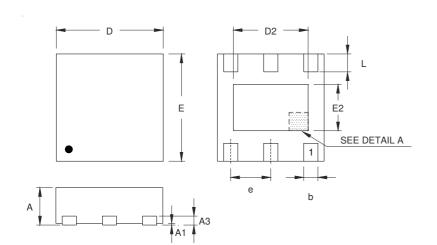


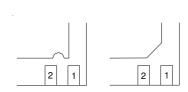
# **Outline Dimension**



Cumbal	Dimensions I	In Millimeters	Dimensions In Inches			
Symbol	Min	Max	Min	Max		
Α	0.889	1.295	0.031	0.051		
A1	0.000	0.152	0.000	0.006		
В	1.397	1.803	0.055	0.071		
b	0.250	0.560	0.010	0.022		
С	2.591	2.997	0.102	0.118		
D	2.692	3.099	0.106	0.122		
е	0.838	1.041	0.033	0.041		
Н	0.080	0.254	0.003	0.010		
L	0.300	0.610	0.012	0.024		

**SOT-23-6 Surface Mount Package** 





**DETAIL A** 

Pin #1 ID and Tie Bar Mark Options

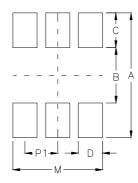
Note: The configuration of the Pin #1 identifier is optional, but must be located within the zone indicated.

Cumbal	Dimensions	In Millimeters	Dimensions In Inches			
Symbol	Min	Max	Min	Max		
Α	0.700	0.800	0.028	0.031		
A1	0.000	0.050	0.000	0.002		
A3	0.175	0.250	0.007	0.010		
b	0.200	0.350	0.008	0.014		
D	1.900	2.100	0.075	0.083		
D2	1.550	1.650	0.061	0.065		
Е	1.900	2.100	0.075	0.083		
E2	0.950	1.050	0.037	0.041		
е	0.650		0.0	)26		
L	0.200	0.300	0.008	0.012		

W-Type 6SL DFN 2x2 Package

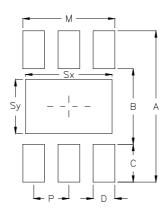


# **Footprint Information**



Package	Number of		Footp	rint Din	nension	(mm)		Tolerance
i ackage	Pin	P1	Α	В	С	D	М	Tolerance
TSOT-26/TSOT-26(FC)/SOT-26/SOT-26(COL)	6	0.95	3.60	1.60	1.00	0.70	2.60	±0.10





	Package Number	Number of	Footprint Dimension (mm)								Tolerance
Fackage	Pin	Р	Α	В	С	D	Sx	Sy	М	Tolerance	
	V/W/U/XDFN2x2-6S	6	0.65	2.80	1.40	0.70	0.40	1.60	1.00	1.70	±0.05

## **Richtek Technology Corporation**

14F, No. 8, Tai Yuen 1 $^{\rm st}$  Street, Chupei City Hsinchu, Taiwan, R.O.C.

Tel: (8863)5526789

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# **Datasheet Revision History**

Version	Date	Description	Item
			General Description on P1
07	2023/2/1	Modify	Features on P1
			Electrical Characteristics on P6